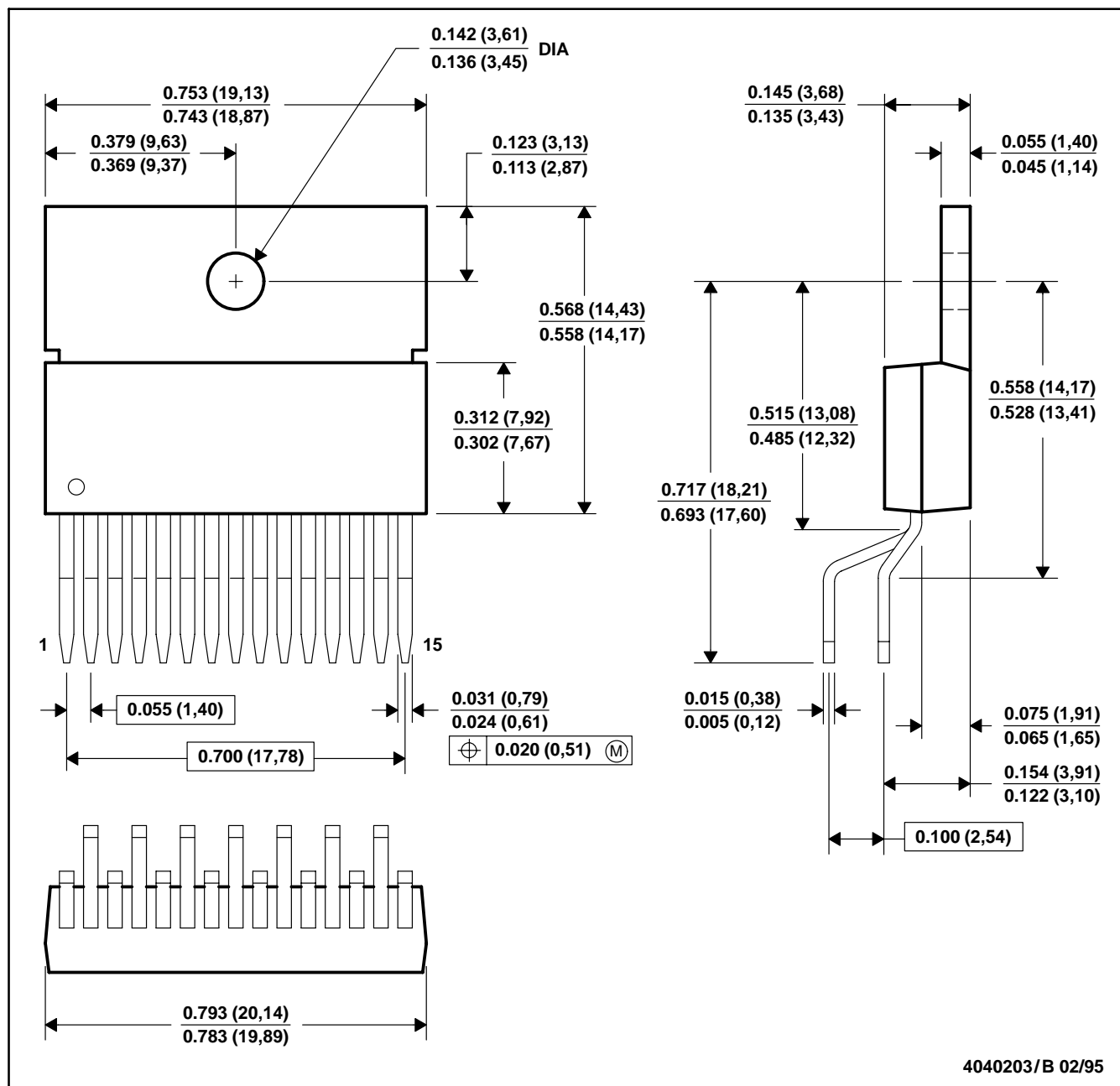


KN (R-PZFM-T15)

PLASTIC FLANGE-MOUNT PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. All lead dimensions apply before solder dip.

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